Three Phase Inverter

DC link active LED indicator

Module Temperature Sense

Reference for Level Shifting

CAUTION HIGH VOLTAGE

CAUTION HOT SURFACE

Engineer: Pawan Nayak

Drawn By: B22

SVN Rev: E1

Number: Public Release

Orderable: TIDA-01456_Inverter_Stage.SchDoc

Inverter and Current Sensing

Three Phase Inverter HV_Class

Phase U Leg Current Sense

Phase V Leg Current Sense

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Isolated Communication Interface

Pin 6 of the header J1 has to be removed during board assembly as a key for the mating connector.

Reinforced Isolation Barrier

C2000 Control Card Interface

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